



### SBR2M30P1

#### 2.0A SBR SURFACE MOUNT SUPER BARRIER RECTIFIER POWERDI

#### **Features**

- Patented Super Barrier Rectifier SBR® Technology
- Ultra Low Leakage Current
- Excellent High Temperature Stability
- Superior Reverse Avalanche Capability
- Patented Interlocking Clip Design for High Surge Current Capacity
- Patented Super Barrier Rectifier Technology
- · Soft, Fast Switching Capability
- +175°C Operating Junction Temperature
- ±16KV ESD Protection (HBM, 3B)
- ±25KV ESD Protection (IEC61000-4-2 Level 4, Air Discharge)
- Lead Free Finish; RoHS Compliant (Note 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: POWERDI<sup>®</sup>123
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity Indicator: Cathode Band
- Terminals: Matte Tin Finish annealed over Copper leadframe.
   Solderable per MIL-STD-202, Method 208 (23)
- Weight: 0.018 grams (Approximate)



Top View

### **Ordering Information** (Note 4)

Part Number	Case	Packaging
SBR2M30P1-7	POWERDI®123	3000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



2M3 = Product Type Marking Code YM = Date Code Marking

Y = Year (ex: C = 2015)

M = Month (ex: 9 = September)

#### Date Code Key

Year	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	Т	U	V	W	Χ	Υ	Z	Α	В	С
Month	Jan	Feb	Mar Ar	or Mav	Jun	Jul	Aua	Sep Oc	t Nov	Dec

 Month
 Jan
 Feb
 Mar
 Apr
 May
 Jun
 Jul
 Aug
 Sep
 Oct
 Nov
 Dec

 Code
 1
 2
 3
 4
 5
 6
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# **Maximum Ratings** ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$		
Working Peak Reverse Voltage	$V_{RWM}$	30	V
DC Blocking Voltage	$V_{RM}$		
RMS Reverse Voltage	$V_{R(RMS)}$	21	V
Average Rectified Output Current (See Figure 1)	Ιο	2.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms	Isou	75	Α
Single Half Sine-Wave Superimposed on Rated Load	IFSM	70	, , , , , , , , , , , , , , , , , , ,
Non-Repetitive Avalanche Energy	F	105	mJ
$(T_J = +25^{\circ}C, I_{AS} = 5A, L = 8.5 \text{ mH})$	Eas	103	1110
Repetitive Peak Avalanche Energy	0	1100	W
(1μs, + 25°C)	Parm	1100	VV

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance Thermal Resistance Junction to Soldering (Note 5) Thermal Resistance Junction to Ambient (Note 6) Thermal Resistance Junction to Ambient (Note 7)	$egin{array}{c} R_{ heta JS} \ R_{ heta JA} \ R_{ heta JA} \end{array}$	5 183 125	<sup>e</sup> C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +175	<sup>o</sup> C

Notes:

- 5. Theoretical R<sub>e,JS</sub> calculated from the top center of the die straight down to the PCB cathode tab solder junction. 6. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf.
- 7. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

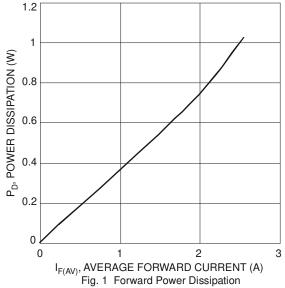
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 8)	V <sub>(BR)R</sub>	30	-	-	V	I <sub>R</sub> = 200μA
Forward Voltage Drop	V <sub>F</sub>	- - - -	0.26 0.37 0.42 0.16 0.29 0.36	0.30 0.41 0.46 0.19 0.32 0.39	V	$\begin{split} &   F = 0.1A, \ T_J = +25^{\circ}C \\ &   F = 1.0A, \ T_J = +25^{\circ}C \\ &   F = 2.0A, \ T_J = +25^{\circ}C \\ &   F = 0.1A, \ T_J = +125^{\circ}C \\ &   F = 1.0A, \ T_J = +125^{\circ}C \\ &   F = 2.0A, \ T_J = +125^{\circ}C \\ \end{split}$
Leakage Current (Note 8)	I <sub>R</sub>	-	10 20 1.7 3.1	100 200 8 12	μΑ μΑ mA mA	$\begin{split} V_R &= 5V,  T_J = +25^{\circ}C \\ V_R &= 30V,  T_J = +25^{\circ}C \\ V_R &= 5V,  T_J = +125^{\circ}C \\ V_R &= 30V,  T_J = +125^{\circ}C \end{split}$

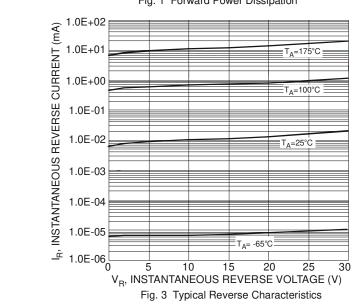
Notes:

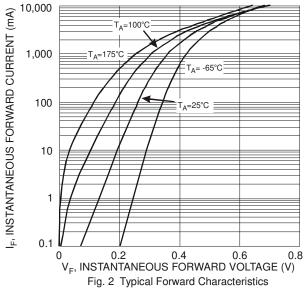
8. Short duration pulse test used to minimize self-heating effect.











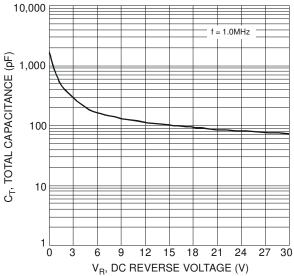
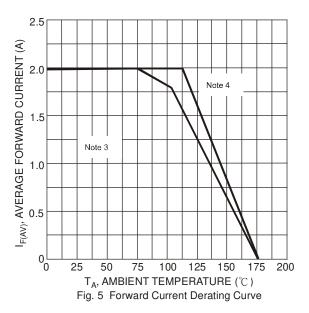
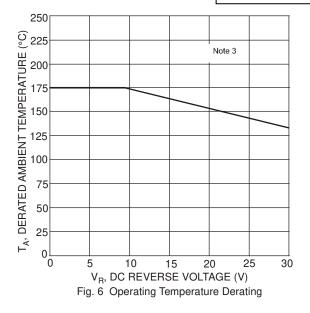


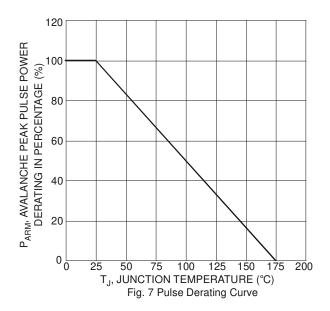
Fig. 4 Total Capacitance vs. Reverse Voltage

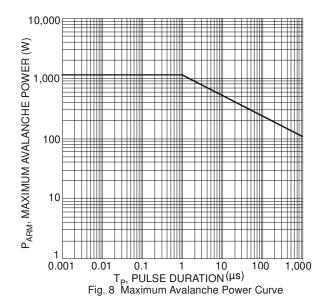














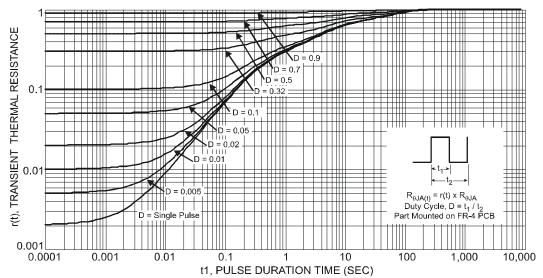


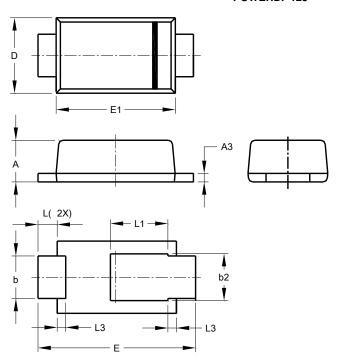
Fig. 9 Transient Thermal Resistance



## **Package Outline Dimensions**

Please see AP02001 at http://www.diodes.com/\_files/datasheets/ap02001.pdf for the latest version.

## POWERDI<sup>®</sup>123

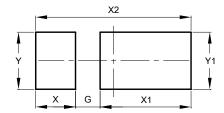


POWERDI <sup>®</sup> 123						
Dim	Min	Max	Тур			
Α	0.93	1.00	0.98			
A3	0.15	0.25	0.20			
b	0.85	1.25	1.00			
b2	1.025	1.125	1.10			
D	1.63	1.93	1.78			
Е	3.50	3.90	3.70			
E1	2.60	3.00	2.80			
L	0.40	0.50	0.45			
L1	1.25	1.40	1.35			
L3	0.125	0.275	0.20			
All Dimensions in mm						

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/\_files/datasheets/ap02001.pdf for the latest version.

#### POWERDI<sup>®</sup>123



Dimensions	value		
Difficitsions	(in mm)		
G	0.65		
X	1.05		
X1	2.40		
X2	4.10		
Υ	1.50		
Y1	1.50		



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